



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: G0202-01 DATE: 2/8/2002 Product Affected: SOIC (20 pins) and SSOP (80 pins) Date Effective: 3/8/2002	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input checked="" type="checkbox"/> Back Mark "K" prefix as assembly location I.D <input type="checkbox"/> Date Code <input type="checkbox"/> Other
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Contact: Geoffrey Cortes Title: Corporate QA / Reliability Manager Phone #: (408) 492- 8321 Fax #: (408) 727-2328 E-mail: Geoffrey.Cortes@idt.com	Attachment:: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: Available upon request
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DESCRIPTION AND PURPOSE OF CHANGE:

Die Technology
 Wafer Fabrication Process
 Assembly Process
 Equipment
 Material
 Testing
 Manufacturing Site To qualify an alternate assembly facility, IDT-Philippines, for SOIC (20 pins) and SSOP (80 pins) plastic packages. There is no change in assembly material.
 Data Sheet
 Other

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT - PCN #: G0202-01

PCN Type: To qualify an alternate assembly facility.

Data Sheet Change: There is no change in Moisture Sensitive Level.

Detail of Change: To qualify an alternate assembly facility, IDT-Philippines, for SOIC (20 pins) and SSOP (80 pins) plastic packages. There is no change in assembly material set.

The products affected are as follows:

SSOP 80 pins (DM80) -- ordering part number ending with "Q3"

SOIC 20 pins (PS20) -- ordering part number ending with "SO"

There is no change in Moisture Sensitive Level.

Conversion Schedule (Estimated)

	Sample Availability	Production Shipments
DM80	Available	3/8/2002
PS20	Available	3/8/2002



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Qualification Plan: P01-11-01 **Expected Completion Date:** 3/8/2002

Test Vehicle: DM80 (SSOP), PS20 (SOIC)

Test Description/Condition	Test Methods	SS /# Fails	DM80 Test Results	PS20 Test Results
Highly Accelerated Stress Test (HAST) (100 Hrs, @ 130°C/85%RH,Static Bias)	EIA/JESD22-A110	45/0	03/01/02	03/01/02
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883 Method 1010	45/0	03/08/02	03/08/02
Auto Clave (SPP) (168Hrs, @ 2ATM, 121°C)	EIA/JESD22-A102	45/0	03/01/02	03/01/02
Physical Dimensions	MIL-STD-883 Method 2016	5/0	5/0	5/0
Resistance to Solvents	MIL-STD-883 Method 2015	3/0	03/01/02	03/01/02
Bake & Ball Shear Test	EIA/JESD22-B116	5/0	5/0	5/0
Bond Pull Test	MIL-STD-883 Method 2011	5/0	5/0	5/0
X-ray Examination	Per IDT specification	45/0	45/0	45/0
S.A.T	JEDEC J-STD-035	10/0	10/0	10/0
External Visual Inspection	MIL-STD-883 Method 2009	25/0	25/0	25/0
Internal Visual Inspection	MIL-STD-883 Method 2010	5/0	5/0	5/0
Moisture Sensitive Level (Level 1)	JEDEC J-STD-020	11/0	11/0	11/0